

Serial No. 10/035,400
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Reply to the Office Action dated October 9, 2003
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This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (previously presented): A method of producing a thin film circuit board used as a milli-wave or micro-wave module, the method comprising steps of:

cleaning a substrate comprising dielectric ceramic, and having a thickness of 0.05 mm to 2 mm and a flexural strength of 500 kgf/cm² to 4000 kgf/cm²;

forming a conductor film in a predetermined pattern on the substrate, said conductor film including at least one selected from Cu, Au, Ag, Al, Ni, Ti, Cr, Ni-Cr, Nb, and V;

forming an insulating film on the substrate to cover the conductor film, said insulating film comprising at least one organic resin selected from polyimide, epoxy resins, benzocyclobutene resins, acrylic resins, and cyclic olefin resins, and having a thickness of 20 μ m or greater, an area of 5 cm² or less per pattern, and a stress of 15 MPa to 60 MPa;

patterning the insulating film; and

repeating the insulating film forming step and the insulating film patterning step more than once.

Claim 2 (previously presented): A method of producing a thin film circuit board according to Claim 1, wherein the insulating film comprises a photosensitive organic film,

said insulating film forming step comprises a step of forming the photosensitive organic film on the substrate, and

said patterning step comprises steps of

exposing and developing the photosensitive organic film by photolithography, and

curing the photosensitive organic film.

Claim 3 (previously presented): A method of producing a thin film circuit board according to Claim 1, wherein the insulating film comprises a non-photosensitive organic film,

said insulating film forming step comprises a step of forming the non-photosensitive organic film on the substrate, and

said patterning step comprises steps of

curing the non-photosensitive organic film,
forming an etching resist on the non-photosensitive organic film,
etching the non-photosensitive organic film by dry etching, and
removing the etching resist.